特点

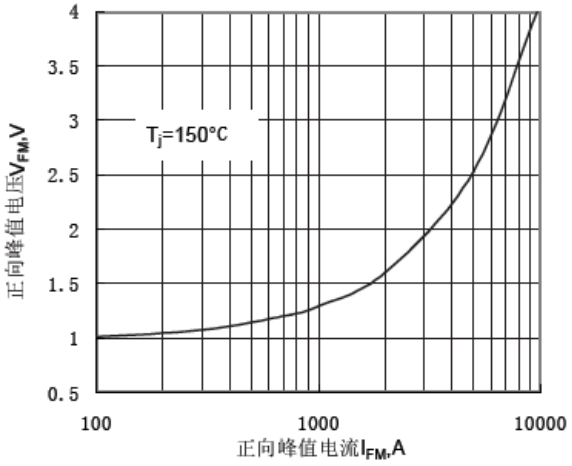
- 全扩散工艺
- 平板型陶瓷管封装
- 双面冷却

典型应用

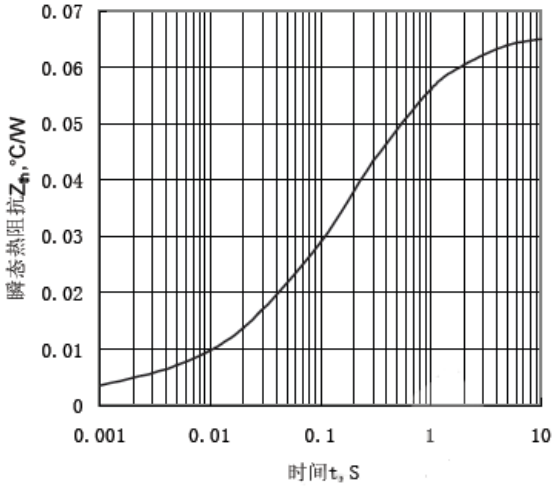
- 大功率变流器
- 焊接设备
- 电机控制和驱动
- 充电设备

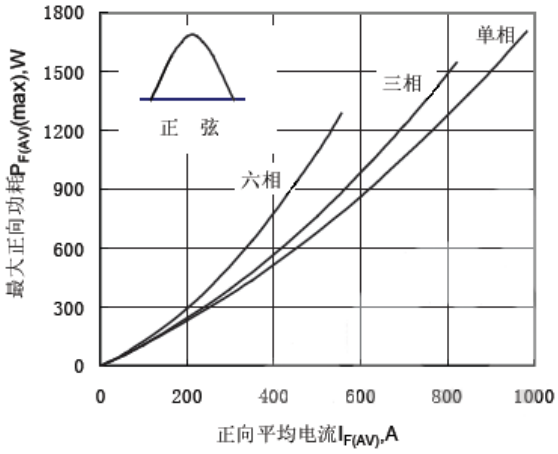
				最小	典型	最大	
	器）	紧力					
	安装力						
	储存　度						
	质量						
	外形						

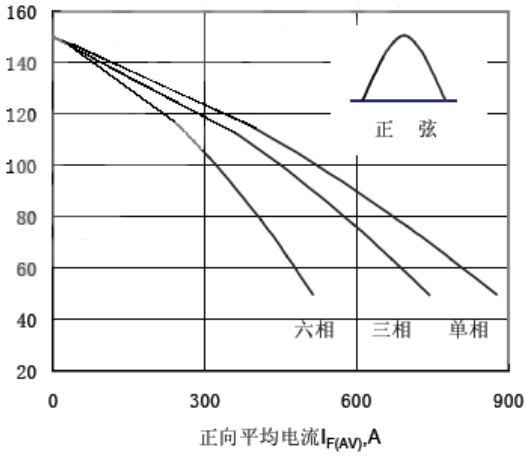
Peak forward Voltage Vs.Peak forward Current



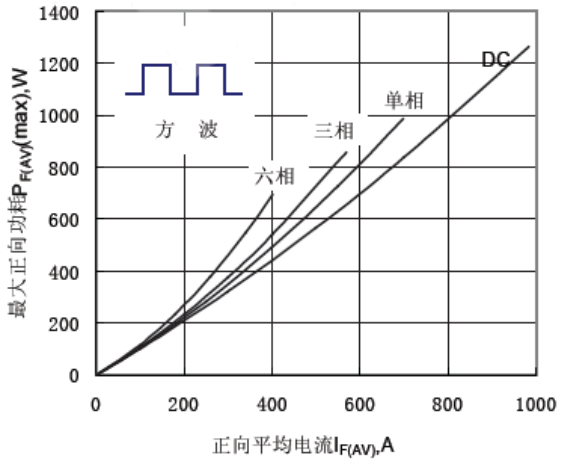
Max. junction To heatsink Thermai Impedance Vs.Time



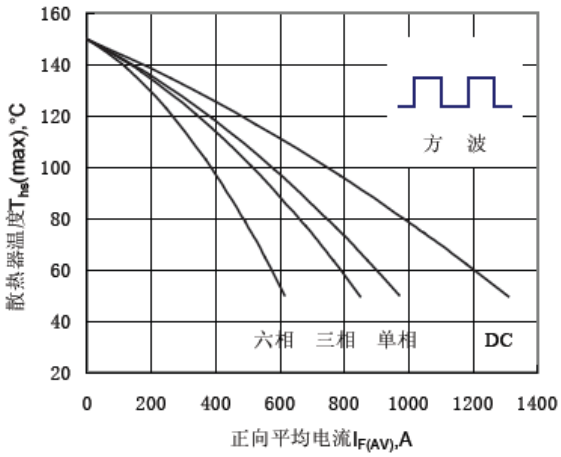


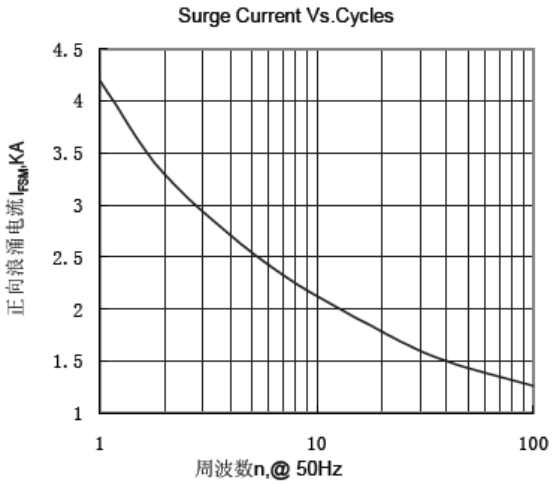


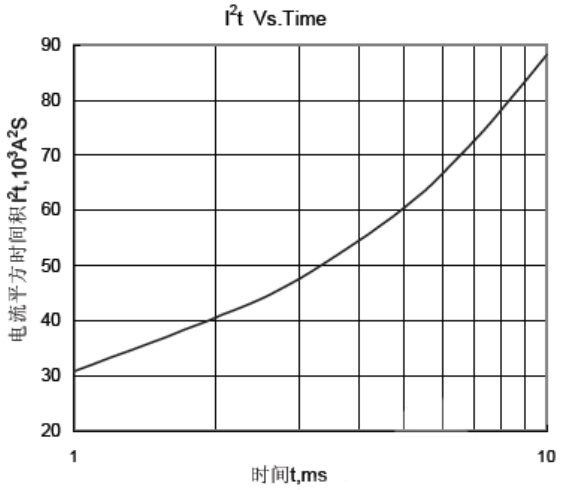
Max. heatsink Temperature Vs.Mean forward Current



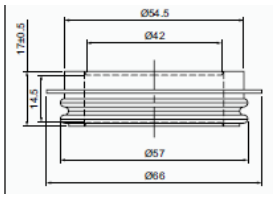
Max. heatsink Temperature Vs.Mean forward Current



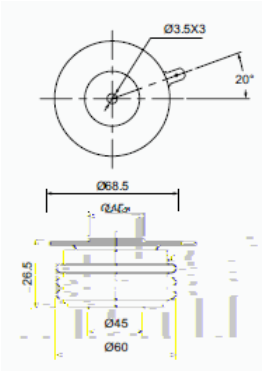

Surge Current Vs.Cycles
正向浪涌电流IFSM,KA
4.5
4
3.5
3
2.5
2
1.5
1
1
10
100
周波数n,@ 50Hz


I2t Vs.Time
电流平方时间积I2t,10³A²S
90
80
70
60
50
40
30
20
1
10
时间t,ms

外形图:


Ø54.5
Ø42
17±0.5
14.5
Ø57
Ø66

图


Ø3.5X3
20°
Ø68.5
26.5
Ø45
Ø60

图